



Description

- Pad-Per-Hole both sides. Plated-thru holes.
- 0.080" diameter isolated solder pad around each hole on both sides.
- Unrestricted component placement and extended area for high density applications.

Specifications

Dimensions (H x W x Thick)	4.00" x 6.00" x 0.062" (101.6mm x 152.4mm x 1.57mm)
Hole Diameter	0.042" (1.067mm) Plated Thru
Grid	0.100" x 0.100" (2.54mm x 2.54mm)
Circuit Pattern	Pad per hole - both sides
Material	FR4
UL Flammability Class	94V-0
16 Pin DIP Capacity	72
Wire-Wrap Terminals	T44, T46, T49, T68
Solder Terminals	T42-1, K24C, K31C
Wire-Wrap Socket Pins	R32

